DATA SHEET

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Product	Cooling for D2912-A

Cooling System for D2912-A
D7000-C100/C110 & D2000-C100

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BTX cooling system consisting of a full aluminium heatsink, backplate and a BTX airduct with integrated fan

Heatsink D7000-C100
Full aluminum
Mounting screws according LGA1156 requirements (M3)
Spring-loaded mounting screws for specified downforce

Backplate D7000-C110
Metal backplate, 1.8mm plus insulating sheet
Complies to standard LGA1156 requirements
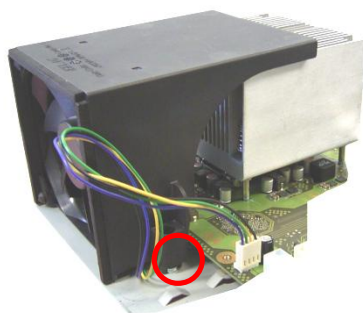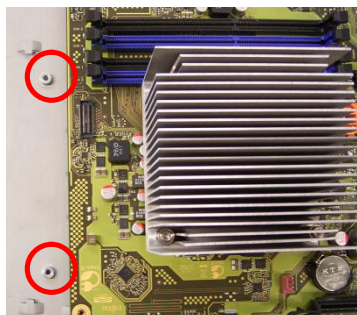M3 screw threads

Airduct / Fan D2000-C100
Plastic airduct, BTX compliant
Fan 92 x 25mm, ball/sleeve bearing, 4 pin PWM
Speed: 700rpm (+/- 300rpm) - 3.600rpm (+/- 10%)
Airflow: 0.39 m^3/min – 2.0 m^3/min
Sound level: 18 dB(A) - 44dB(A) max.
MTBF: ~ 40.000hrs

Supported processors
Intel processors (socket LGA1156) up to 95W TDP

Mechanical requirements
BTX chassis w/o SRM (Support Retention Module).
Chassis must provide 2 screw threads (UNC 6-32) for airduct mounting

BTX Cooling System offered by Fujitsu
Technology Solutions in cooperation with EKL AG

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